



Material Content Data Sheet



Sales Product Name	TLE4253GS			Issued	20. July 2018			
MA#	MA001370036							
Package	PG-DSO-8-46			Weight*	83.04 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.205	2.66	2.66	26551	26551
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		436	
	non noble metal	iron	7439-89-6	0.723	0.87		8711	
wire	non noble metal	copper	7440-50-8	29.372	35.37	36.29	353722	362978
	non noble metal	copper	7440-50-8	0.069	0.08	0.08	832	832
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1165
encapsulation	plastics	epoxy resin	-	4.450	5.36		53587	
	inorganic material	silicondioxide	60676-86-0	43.819	52.78	58.26	527718	582470
leadfinish	non noble metal	tin	7440-31-5	0.824	0.99	0.99	9924	9924
plating	noble metal	silver	7440-22-4	0.144	0.17	0.17	1736	1736
glue	plastics	epoxy resin	-	0.322	0.39		3877	
	noble metal	silver	7440-22-4	0.966	1.16	1.55	11632	15509
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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